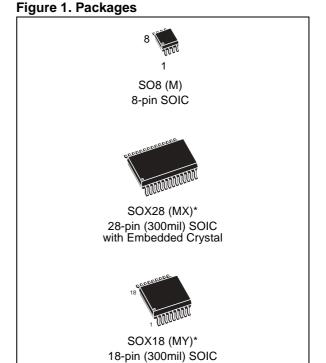


# Serial Access Real-Time Clock with Alarms

#### **FEATURES SUMMARY**

- 2.0 TO 5.5V CLOCK OPERATING VOLTAGE
- COUNTERS FOR TENTHS/HUNDREDTHS OF SECONDS, SECONDS, MINUTES, HOURS, DAY, DATE, MONTH, YEAR, AND CENTURY
- AUTOMATIC SWITCH-OVER AND DESELECT CIRCUITRY
- SERIAL INTERFACE SUPPORTS I<sup>2</sup>C BUS (400kHz PROTOCOL)
- PROGRAMMABLE ALARM AND INTERRUPT FUNCTION (VALID EVEN DURING BATTERY BACK-UP MODE)
- WATCHDOG TIMER
- POWER-DOWN TIME-STAMP (HT Bit)
- LOW OPERATING CURRENT OF 400µA
- BATTERY BACK-UP NOT RECOMMENDED FOR 3.0V APPLICATIONS (CAPACITOR BACK-UP ONLY)
- BATTERY OR SUPER-CAP BACK-UP
- OPERATING TEMPERATURE OF –40 TO 85°C
- ULTRA-LOW BATTERY SUPPLY CURRENT OF 1μA
- PACKAGE OPTIONS INCLUDE A 28-LEAD OR 18-LEAD EMBEDDED CRYSTAL SOIC



with Embedded Crystal

June 2004 1/30

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#### SUMMARY DESCRIPTION

The M41T81 Serial Access TIMEKEEPER® SRAM is a low power Serial RTC with a built-in 32.768kHz oscillator (external crystal controlled). Eight bytes of the SRAM (see Table 2., page 13) are used for the clock/calendar function and are configured in binary coded decimal (BCD) format. An additional 12 bytes of SRAM provide status/control of Alarm, Watchdog and Square Wave functions. Addresses and data are transferred serially via a two line, bi-directional I<sup>2</sup>C interface. The built-in address register is incremented automatically after each WRITE or READ data byte.

The M41T81 has a built-in power sense circuit which detects power failures and automatically switches to the battery supply when a power failure occurs. The energy needed to sustain the SRAM and clock operations can be supplied by a

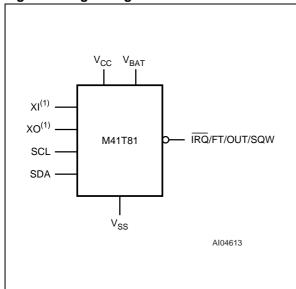
small lithium button supply when a power failure occurs.

Functions available to the user include a non-volatile, time-of-day clock/calendar, Alarm interrupts, Watchdog Timer and programmable Square Wave output. The eight clock address locations contain the century, year, month, date, day, hour, minute, second and tenths/hundredths of a second in 24 hour BCD format. Corrections for 28, 29 (leap year - valid until year 2100), 30 and 31 day months are made automatically.

The M41T81 is supplied in either an 8-pin SOIC or an 18-pin (MY) or 28-pin (MX), 300mil SOIC package which includes an embedded 32kHz crystal.

The 18-pin and 28-pin, embedded crystal SOIC requires only a user-supplied battery to provide non-volatile operation.

Figure 2. Logic Diagram



Note: 1. For SO8 package only.

**Table 1. Signal Names** 

XI <sup>(1)</sup>	Oscillator Input
XO <sup>(1)</sup>	Oscillator Output
ĪRQ/OUT/ FT/SQW	Interrupt / Output Driver / Frequency Test / Square Wave (Open Drain)
SDA	Serial Data Input/Output
SCL	Serial Clock Input
V <sub>BAT</sub>	Battery Supply Voltage
V <sub>CC</sub>	Supply Voltage
V <sub>SS</sub>	Ground
NC	No Connect
NF	No Function

Note: 1. For SO8 package only.

Figure 3. 8-pin SOIC (M) Connections

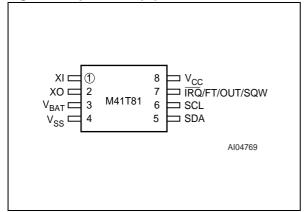
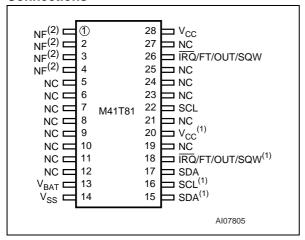


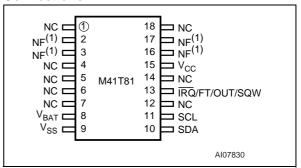
Figure 4. 28-pin, 300mil SOIC (MX) Connections



Note: 1. No Connect (NC) pin for 28-pin SOIC, but should be considered to have indicated function in anticipation of replacement with 18-pin SOIC.

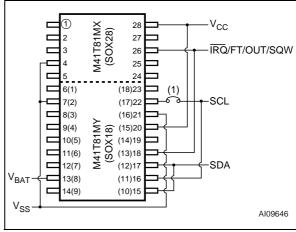
 No Function (NF) pins should be tied to V<sub>SS</sub>. Pins 1, 2, 3, and 4 are internally shorted together.

# Figure 5. 18-pin, 300mil SOIC (MY) Connections



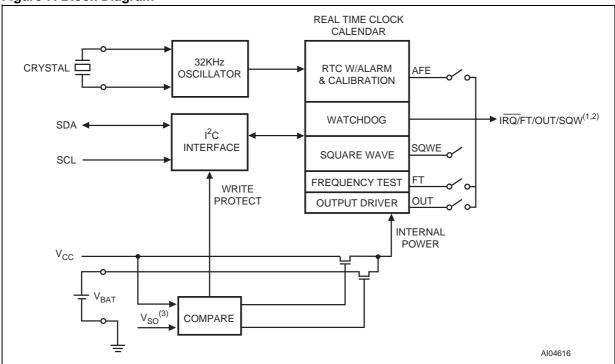
Note: 1. NF pins must be tied to  $V_{SS}$ . Pins 2 and 3, 16, and 17 are internally shorted together.

# Figure 6. Dual Footprint Connections (28-pin to 18-pin)



Note: 1. Remove this jumper for SOX18.

Figure 7. Block Diagram



Note: 1. Open drain output

- 2. Square Wave function has the highest priority on IRQ/FT/OUT/SQW output.
- 3.  $V_{SO} = V_{BAT} 0.5V$  (typ)

#### **OPERATION**

The M41T81 clock operates as a slave device on the serial bus. Access is obtained by implementing a start condition followed by the correct slave address (D0h). The 20 bytes contained in the device can then be accessed sequentially in the following order:

- 1. Tenths/Hundredths of a Second Register
- 2. Seconds Register
- 3. Minutes Register
- 4. Century/Hours Register
- 5. Day Register
- 6. Date Register
- 7. Month Register
- 8. Year Register
- Control Register
- 10. Watchdog Register
- 11 16. Alarm Registers
- 17 19. Reserved
- 20. Square Wave Register

The M41T81 clock continually monitors  $V_{CC}$  for an out-of-tolerance condition. Should  $V_{CC}$  fall below  $V_{SO}$ , the device terminates an access in progress and resets the device address counter. Inputs to the device will not be recognized at this time to prevent erroneous data from being written to the device from a an out-of-tolerance system. The device also automatically switches over to the battery and powers down into an ultra low current mode of operation to conserve battery life. As system power returns and  $V_{CC}$  rises above  $V_{SO}$ , the battery is disconnected, and the power supply is switched to external  $V_{CC}$ .

For more information on Battery Storage Life refer to Application Note AN1012.

#### 2-Wire Bus Characteristics

The bus is intended for communication between different ICs. It consists of two lines: a bi-directional data signal (SDA) and a clock signal (SCL). Both the SDA and SCL lines must be connected to a positive supply voltage via a pull-up resistor.

The following protocol has been defined:

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is High.
- Changes in the data line, while the clock line is High, will be interpreted as control signals.

Accordingly, the following bus conditions have been defined:

**Bus not busy.** Both data and clock lines remain High.

**Start data transfer.** A change in the state of the data line, from high to Low, while the clock is High, defines the START condition.

**Stop data transfer.** A change in the state of the data line, from Low to High, while the clock is High, defines the STOP condition.

**Data Valid.** The state of the data line represents valid data when after a start condition, the data line is stable for the duration of the high period of the clock signal. The data on the line may be changed during the Low period of the clock signal. There is one clock pulse per bit of data.

Each data transfer is initiated with a start condition and terminated with a stop condition. The number of data bytes transferred between the start and stop conditions is not limited. The information is transmitted byte-wide and each receiver acknowledges with a ninth bit.

By definition a device that gives out a message is called "transmitter," the receiving device that gets the message is called "receiver." The device that controls the message is called "master." The devices that are controlled by the master are called "slaves."

Acknowledge. Each byte of eight bits is followed by one Acknowledge Bit. This Acknowledge Bit is a low level put on the bus by the receiver whereas the master generates an extra acknowledge related clock pulse. A slave receiver which is addressed is obliged to generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter.

The device that acknowledges has to pull down the SDA line during the acknowledge clock pulse in such a way that the SDA line is a stable Low during the High period of the acknowledge related clock pulse. Of course, setup and hold times must be taken into account. A master receiver must signal an end of data to the slave transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this case the transmitter must leave the data line High to enable the master to generate the STOP condition.

Figure 8. Serial Bus Data Transfer Sequence

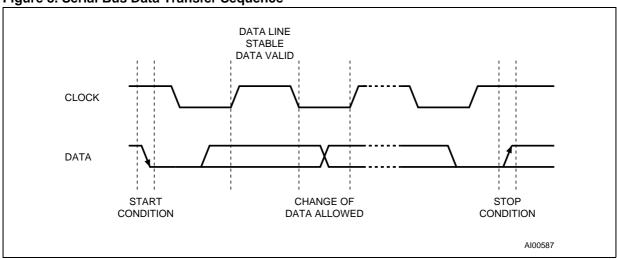
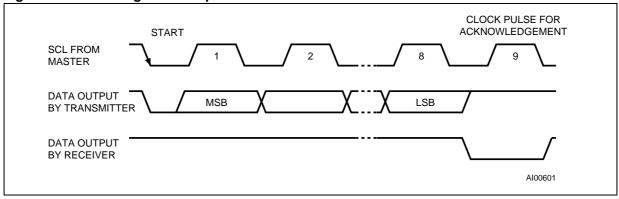


Figure 9. Acknowledgement Sequence



#### **READ Mode**

In this mode the master reads the M41T81 slave after setting the slave address (see Figure 11., page 10). Following the WRITE Mode Control Bit (R/W=0) and the Acknowledge Bit, the word address 'An' is written to the on-chip address pointer. Next the START condition and slave address are repeated followed by the READ Mode Control Bit (R/W=1). At this point the master transmitter becomes the master receiver. The data byte which was addressed will be transmitted and the master receiver will send an Acknowledge Bit to the slave transmitter. The address pointer is only incremented on reception of an Acknowledge Clock. The M41T81 slave transmitter will now place the data byte at address An+1 on the bus, the master receiver reads and acknowledges the new byte and the address pointer is incremented to "An+2."

This cycle of reading consecutive addresses will continue until the master receiver sends a STOP condition to the slave transmitter.

The system-to-user transfer of clock data will be halted whenever the address being read is a clock address (00h to 07h). The update will resume due to a Stop Condition or when the pointer increments to any non-clock address (08h-13h).

**Note:** This is true both in READ Mode and WRITE Mode.

An alternate READ Mode may also be implemented whereby the master reads the M41T81 slave without first writing to the (volatile) address pointer. The first address that is read is the last one stored in the pointer (see Figure 12., page 10).

Figure 10. Slave Address Location

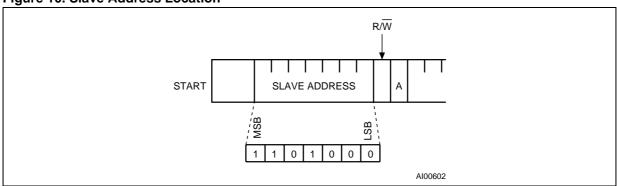


Figure 11. READ Mode Sequence

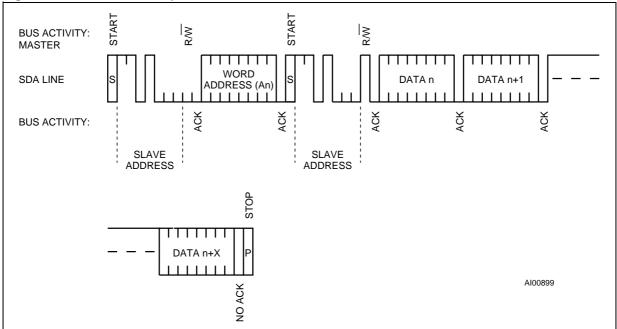
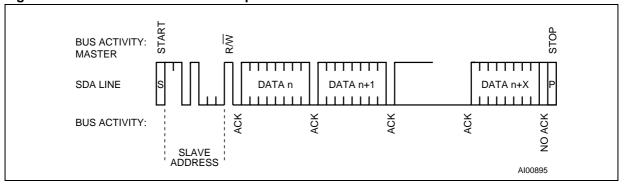


Figure 12. Alternative READ Mode Sequence



#### **WRITE Mode**

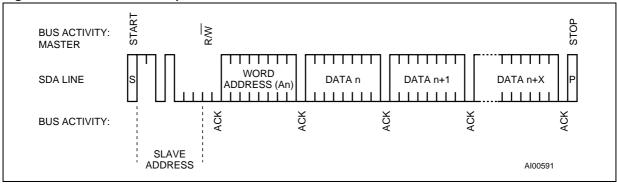
In this mode the master transmitter transmits to the M41T81 slave receiver. Bus protocol is shown in Figure 13., page 11. Following the START condition and slave address, a logic '0' (R/W=0) is placed on the bus and indicates to the addressed device that word address "An" will follow and is to be written to the on-chip address pointer. The data word to be written to the memory is strobed in next and the internal address pointer is incremented to the next address location on the reception of an acknowledge clock. The M41T81 slave receiver will send an acknowledge clock to the master transmitter after it has received the slave address see Figure 10., page 9 and again after it has received the word address and each data byte.

#### **Data Retention Mode**

With valid  $V_{CC}$  applied, the M41T81 can be accessed as described above with READ or WRITE Cycles. Should the supply voltage decay, the power input will be switched from the  $V_{CC}$  pin to the battery when  $V_{CC}$  falls below the Battery Back-up Switchover Voltage ( $V_{SO}$ ). At this time the clock registers will be maintained by the attached battery supply. On power-up, when  $V_{CC}$  returns to a nominal value, write protection continues for  $t_{rec}$ . For a further, more detailed review of lifetime cal-

For a further, more detailed review of lifetime calculations, please see Application Note AN1012.

Figure 13. WRITE Mode Sequence



#### **CLOCK OPERATION**

The 20-byte Register Map (see Table 2., page 13) is used to both set the clock and to read the date and time from the clock, in a binary coded decimal format. Tenths/Hundredths of Seconds, Seconds, Minutes, and Hours are contained within the first four registers.

**Note:** The Tenths/Hundredths of Seconds cannot be written to any value other than "00."

Bits D6 and D7 of Clock Register 03h (Century/ Hours Register) contain the CENTURY ENABLE Bit (CEB) and the CENTURY Bit (CB). Setting CEB to a '1' will cause CB to toggle, either from '0' to '1' or from '1' to '0' at the turn of the century (depending upon its initial state). If CEB is set to a '0,' CB will not toggle. Bits D0 through D2 of Register 04h contain the Day (day of week). Registers 05h, 06h, and 07h contain the Date (day of month), Month and Years. The ninth clock register is the Control Register (this is described in the Clock Calibration section). Bit D7 of Register 01h contains the STOP Bit (ST). Setting this bit to a '1' will cause the oscillator to stop. If the device is expected to spend a significant amount of time on the shelf, the oscillator may be stopped to reduce current drain. When reset to a '0' the oscillator restarts within one second.

The eight Clock Registers may be read one byte at a time, or in a sequential block. Provision has been made to assure that a clock update does not occur while any of the eight clock addresses are being read. If a clock address is being read, an update of the clock registers will be halted. This will prevent a transition of data during the READ.

#### Power-down Time-Stamp

When a power failure occurs, the HT Bit will automatically be set to a '1.' This will prevent the clock from updating the TIMEKEEPER® registers, and will allow the user to read the exact time of the power-down event. Resetting the HT Bit to a '0' will allow the clock to update the TIMEKEEPER registers with the current time. For more information, see Application Note AN1572.

# TIMEKEEPER® Registers

The M41T81 offers 20 internal registers which contain Clock, Alarm, Watchdog, Flag, Square Wave and Control data. These registers are memory locations which contain external (user accessible) and internal copies of the data (usually referred to as BiPORT™ TIMEKEEPER cells). The external copies are independent of internal functions except that they are updated periodically by the simultaneous transfer of the incremented internal copy. The internal divider (or clock) chain will be reset upon the completion of a WRITE to any clock address.

The system-to-user transfer of clock data will be halted whenever the address being read is a clock address (00h to 07h). The update will resume either due to a Stop Condition or when the pointer increments to any non-clock address (08h-13h).

TIMEKEEPER and Alarm Registers store data in BCD. Control, Watchdog and Square Wave Registers store data in Binary Format.

Table 2. TIMEKEEPER® Register Map

Addr									Function	n/Range
	D7	D6	D5	D4	D3	D2	D1	D0	BCD F	ormat
00h		0.1 Se	conds			0.01 S	Seconds	00-99		
01h	ST	,	10 Second	S		Sec	onds		Seconds	00-59
02h	0		10 Minutes	3		Min	utes		Minutes	00-59
03h	CEB	СВ	10 F	10 Hours		Hours (24 F	lour Forma	t)	Century/ Hours	0-1/00-23
04h	0	0	0	0	0	Г	Day of Wee	k	Day	01-7
05h	0	0	10 [	Date		Date: Day	of Month		Date	01-31
06h	0	0	0	10M		Мо	nth		Month	01-12
07h		10 Years Year				Year	00-99			
08h	OUT	FT	S			Calibration			Control	
09h	0	BMB4	BMB3	BMB2	BMB1	BMB0	RB1	RB0	Watchdog	
0Ah	AFE	SQWE	ABE	Al 10M		Alarm	Month		Al Month	01-12
0Bh	RPT4	RPT5	AI 10	Date		Alarm	Date		Al Date	01-31
0Ch	RPT3	HT	AI 10	Al 10 Hour		Alarm	Hour		Al Hour	00-23
0Dh	RPT2	Ala	rm 10 Minu	utes		Alarm I	Minutes		Al Min	00-59
0Eh	RPT1	Alaı	m 10 Seco	onds		Alarm S	Seconds		Al Sec	00-59
0Fh	WDF	AF	0	0	0 0 0 0		Flags			
10h	0	0	0	0	0 0 0 0		Reserved			
11h	0	0	0	0	0 0 0 0		0	Reserved		
12h	0	0	0	0	0 0 0 0		Reserved			
13h	RS3	RS2	RS1	RS0	0	0	0	0	SQW	

Keys: S = Sign Bit

FT = Frequency Test Bit

ST = Stop Bit

0 = Must be set to '0'

BMB0-BMB4 = Watchdog Multiplier Bits

CEB = Century Enable Bit

CB = Century Bit

OUT = Output level

ABE = Alarm in Battery Back-up Mode Enable Bit

AFE = Alarm Flag Enable Flag
RB0-RB1 = Watchdog Resolution Bits
RPT1-RPT5 = Alarm Repeat Mode Bits
WDF = Watchdog Flag (Read only)
AF = Alarm Flag (Read only)
SQWE = Square Wave Enable
RS0-RS3 = SQW Frequency
HT = Halt Update Bit

#### Calibrating the Clock

The M41T81 is driven by a quartz controlled oscillator with a nominal frequency of 32,768Hz. The devices are tested not exceed -25 to +45 ppm (parts per million) oscillator frequency error at 25°C, which equates to about +1.9 to -1.1 minutes per month (see Figure 14., page 15). When the Calibration circuit is properly employed, accuracy improves to better than ±2 ppm at 25°C.

The oscillation rate of crystals changes with temperature. The M41T81 design employs periodic counter correction. The calibration circuit adds or subtracts counts from the oscillator divider circuit at the divide by 256 stage, as shown in Figure 15., page 15. The number of times pulses which are blanked (subtracted, negative calibration) or split (added, positive calibration) depends upon the value loaded into the five Calibration Bits found in the Control Register. Adding counts speeds the clock up, subtracting counts slows the clock down.

The Calibration Bits occupy the five lower order bits (D4-D0) in the Control Register 08h. These bits can be set to represent any value between 0 and 31 in binary form. Bit D5 is a Sign Bit; '1' indicates positive calibration, '0' indicates negative calibration. Calibration occurs within a 64 minute cycle. The first 62 minutes in the cycle may, once per minute, have one second either shortened by 128 or lengthened by 256 oscillator cycles. If a binary '1' is loaded into the register, only the first 2 minutes in the 64 minute cycle will be modified; if a binary 6 is loaded, the first 12 will be affected, and so on.

Therefore, each calibration step has the effect of adding 512 or subtracting 256 oscillator cycles for every 125,829,120 actual oscillator cycles, that is +4.068 or -2.034 ppm of adjustment per calibration step in the calibration register (see Figure 15., page 15). Assuming that the oscillator is running at exactly 32,768Hz, each of the 31 increments in the Calibration byte would represent

+10.7 or -5.35 seconds per month which corresponds to a total range of +5.5 or -2.75 minutes per month.

Two methods are available for ascertaining how much calibration a given M41T81 may require.

The first involves setting the clock, letting it run for a month and comparing it to a known accurate reference and recording deviation over a fixed period of time. Calibration values, including the number of seconds lost or gained in a given period, can be found in Application Note AN934, "TIMEKEEP-ER® CALIBRATION." This allows the designer to give the end user the ability to calibrate the clock as the environment requires, even if the final product is packaged in a non-user serviceable enclosure. The designer could provide a simple utility that accesses the Calibration byte.

The second approach is better suited to a manufacturing environment, and involves the use of the IRQ/FT/OUT/SQW pin. The pin will toggle at 512Hz, when the Stop Bit (ST, D7 of 01h) is '0,' the Frequency Test Bit (FT, D6 of 08h) is '1,' the Alarm Flag Enable Bit (AFE, D7 of 0Ah) is '0,' and the Square Wave Enable Bit (SQWE, D6 of 0Ah) is '0' and the Watchdog Register (09h = 0) is reset.

Any deviation from 512Hz indicates the degree and direction of oscillator frequency shift at the test temperature. For example, a reading of 512.010124Hz would indicate a +20 ppm oscillator frequency error, requiring a –10 (XX001010) to be loaded into the Calibration Byte for correction. Note that setting or changing the Calibration Byte does not affect the Frequency Test output frequency.

The IRQ/FT/OUT/SQW pin is an open drain output which requires a pull-up resistor to  $V_{CC}$  for proper operation. A 500-10k resistor is recommended in order to control the rise time. The FT Bit is cleared on power-down.



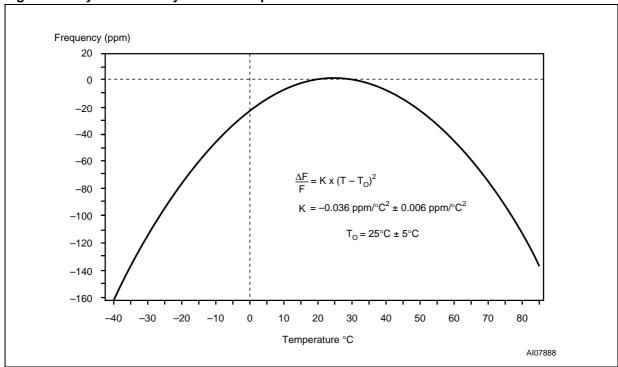
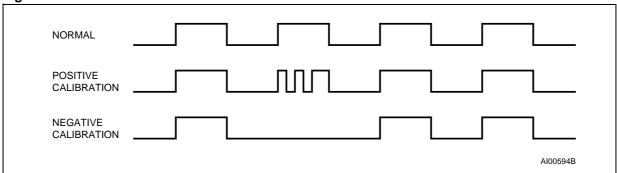


Figure 15. Clock Calibration



#### **Setting Alarm Clock Registers**

Address locations 0Ah-0Eh contain the alarm settings. The alarm can be configured to go off at a prescribed time on a specific month, date, hour, minute, or second or repeat every year, month, day, hour, minute, or second. It can also be programmed to go off while the M41T81 is in the battery back-up mode to serve as a system wake-up call.

Bits RPT5-RPT1 put the alarm in the repeat mode of operation. Table 3., page 17 shows the possible configurations. Codes not listed in the table default to the once per second mode to quickly alert the user of an incorrect alarm setting.

When the clock information matches the alarm clock settings based on the match criteria defined by RPT5-RPT1, the AF (Alarm Flag) is set. If AFE (Alarm Flag Enable) is also set (and <u>SQW</u>E is '0.'), the alarm condition activates the IRQ/FT/OUT/SQW pin.

**Note:** If the address pointer is allowed to increment to the Flag Register address, an alarm condition will not cause the Interrupt/Flag to occur until the address pointer is moved to a different address. It should also be noted that if the last address written is the "Alarm Seconds," the address pointer will increment to the Flag address, causing this situation to occur.

The IRQ/FT/OUT/SQW output is cleared by a READ to the Flags Register as shown in Figure 16. A subsequent READ of the Flags Register is necessary to see that the value of the Alarm Flag has been reset to '0.'

The IRQ/FT/OUT/SQW pin can also <u>be</u> activated in the battery back-up mode. The IRQ/FT/OUT/SQW will go low if an alarm occurs and both ABE (Alarm in Battery Back-up Mode Enable) and AFE are set. Figure 17 illustrates the back-up mode alarm timing.

Figure 16. Alarm Interrupt Reset Waveform

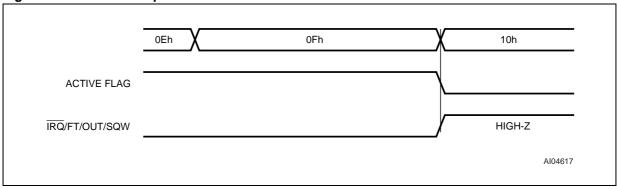
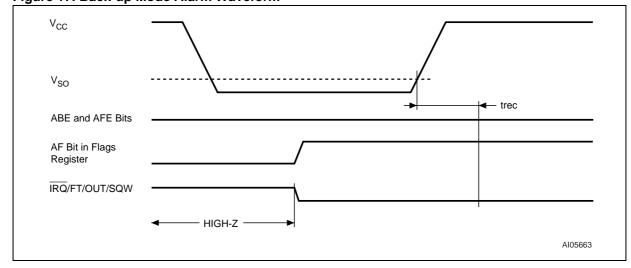


Figure 17. Back-up Mode Alarm Waveform



**Table 3. Alarm Repeat Modes** 

RPT5	RPT4	RPT3	RPT2	RPT1	Alarm Setting
1	1	1	1	1	Once per Second
1	1	1	1	0	Once per Minute
1	1	1	0	0	Once per Hour
1	1	0	0	0	Once per Day
1	0	0	0	0	Once per Month
0	0	0	0	0	Once per Year

#### **Watchdog Timer**

The watchdog timer can be used to detect an out-of-control microprocessor. The user programs the watchdog timer by setting the desired amount of time-out into the Watchdog Register, address 09h. Bits BMB4-BMB0 store a binary multiplier and the two lower order bits RB1-RB0 select the resolution, where 00 = 1/16 second, 01 = 1/4 second, 10 = 1 second, and 11 = 4 seconds. The amount of time-out is then determined to be the multiplication of the five-bit multiplier value with the resolution. (For example: writing 00001110 in the Watchdog Register = 3\*1, or 3 seconds). If the processor does not reset the timer within the specified period, the M41T81 sets the WDF (Watchdog Flag) and generates a watchdog interrupt.

The watchdog timer can be reset by having the microprocessor perform a WRITE of the Watchdog Register. The time-out period then starts over.

Should the watchdog timer time-out, a value of 00h needs to be written to the Watchdog Register in order to clear the IRQ/FT/OUT/SQW pin. This will also disable the watchdog function until it is again programmed correctly. A READ of the Flags Register will reset the Watchdog Flag (Bit D7; Register 0Fh).

The watchdog function is automatically disabled upon power-up and the Watchdog Register is cleared. If the watchdog function is set, the frequency test function is activated, and the SQWE Bit is '0,' the watchdog function prevails and the frequency test function is denied.

# **Square Wave Output**

The M41T81 offers the user a programmable square wave function which is output on the SQW pin. RS3-RS0 bits located in 13h establish the square wave output frequency. These frequencies are listed in Table 4. Once the selection of the

SQW frequency has been completed, the IRQ/FT/OUT/SQW pin can be turned on and off under software control with the Square Wave Enable Bit (SQWE) located in Register 0Ah.

**Table 4. Square Wave Output Frequency** 

	Square \	Squar	e Wave		
RS3	RS2	RS1	RS0	Frequency	Units
0	0	0	0	None	-
0	0	0	1	32.768	kHz
0	0	1	0	8.192	kHz
0	0	1	1	4.096	kHz
0	1	0	0	2.048	kHz
0	1	0	1	1.024	kHz
0	1	1	0	512	Hz
0	1	1	1	256	Hz
1	0	0	0	128	Hz
1	0	0	1	64	Hz
1	0	1	0	32	Hz
1	0	1	1	16	Hz
1	1	0	0	8	Hz
1	1	0	1	4	Hz
1	1	1	0	2	Hz
1	1	1	1	1	Hz

## **Century Bit**

Bits D7 and D6 of Clock Register 03h contain the CENTURY ENABLE Bit (CEB) and the CENTURY Bit (CB). Setting CEB to a '1' will cause CB to toggle, either from a '0' to '1' or from '1' to '0' at the turn of the century (depending upon its initial state). If CEB is set to a '0,' CB will not toggle.

#### **Output Driver Pin**

When the FT Bit, AFE Bit, SQWE Bit, and Watchdog Register are not set, the IRQ/FT/OUT/SQW pin becomes an output driver that reflects the contents of D7 of the Control Register. In other words, when D7 (OUT Bit) and D6 (FT\_Bit) of address location 08h are a '0,' then the IRQ/FT/OUT/SQW pin will be driven low.

**Note:** The IRQ/FT/OUT/SQW pin is an open drain which requires an external pull-up resistor.

#### **Preferred Initial Power-on Default**

Upon initial application of power to the device, the following register bits are set to a '0' state: Watchdog Register; AFE; ABE; SQWE; and FT. The following bits are set to a '1' state: ST; OUT; and HT (see Table 5., page 19).

**Table 5. Preferred Default Values** 

Condition	ST	нт	Out	FT	AFE	SQWE	ABE	WATCHDOG Register <sup>(1)</sup>
Initial Power-up <sup>(2)</sup>	1	1	1	0	0	0	0	0
Subsequent Power-up (with battery back-up) <sup>(3)</sup>	UC	1	UC	0	UC	UC	UC	0

Note: 1. BMB0-BMB4, RB0, RB1.

- 2. State of other control bits undefined.
- 3. UC = Unchanged

## **MAXIMUM RATING**

Stressing the device above the rating listed in the "Absolute Maximum Ratings" table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is

not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

**Table 6. Absolute Maximum Ratings** 

Sym	Parameter	Value	Unit	
T <sub>STG</sub>	Storage Temperature (V <sub>CC</sub> Off, Oscillator Off)	-55 to 125	°C	
V <sub>CC</sub>	Supply Voltage	-0.3 to 7	V	
T <sub>SLD</sub> <sup>(1,2)</sup>	Lead Solder Temperature for 10 Seconds	260	°C	
V <sub>IO</sub>	Input or Output Voltages	-0.3 to Vcc+0.3	V	
Io	Output Current		20	mA
PD	Power Dissipation	1	W	

Note: 1. For SO package, standard (SnPb) lead finish: Reflow at peak temperature of 225°C (total thermal budget not to exceed 180°C for

CAUTION: Negative undershoots below -0.3 volts are not allowed on any pin while in the Battery Back-up Mode

between 90 to 150 seconds).

2. For SO package, Lead-free (Pb-free) lead finish: Reflow at peak temperature of 260°C (total thermal budget not to exceed 245°C for greater than 30 seconds).

# DC AND AC PARAMETERS

This section summarizes the operating and measurement conditions, as well as the DC and AC characteristics of the device. The parameters in the following DC and AC Characteristic tables are derived from tests performed under the Measure-

ment Conditions listed in the relevant tables. Designers should check that the operating conditions in their projects match the measurement conditions when using the quoted parameters.

**Table 7. Operating and AC Measurement Conditions** 

Parameter	M41T81
Supply Voltage (Vcc)	2.0 to 5.5V
Ambient Operating Temperature (T <sub>A</sub> )	−40 to 85°C
Load Capacitance (C <sub>L</sub> )	100pF
Input Rise and Fall Times	≤ 50ns
Input Pulse Voltages	0.2V <sub>CC</sub> to 0.8 V <sub>CC</sub>
Input and Output Timing Ref. Voltages	0.3V <sub>CC</sub> to 0.7 V <sub>CC</sub>

Note: Output Hi-Z is defined as the point where data is no longer driven.

Figure 18. AC Measurement I/O Waveform

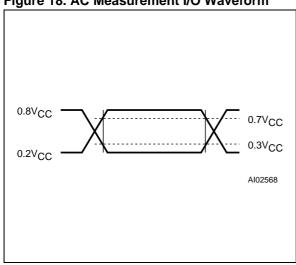


Table 8. Capacitance

Symbol	Parameter <sup>(1,2)</sup>	Min	Max	Unit
C <sub>IN</sub>	Input Capacitance		7	pF
C <sub>OUT</sub> <sup>(3)</sup>	Output Capacitance		10	pF
t <sub>LP</sub>	Low-pass filter input time constant (SDA and SCL)		50	ns

Note: 1. Effective capacitance measured with power supply at 5V; sampled only, not 100% tested.

- 2. At 25°C, f = 1MHz.
- 3. Outputs deselected.

**Table 9. DC Characteristics** 

Sym	Parameter	Test Condition <sup>(1)</sup>	Min	Тур	Max	Unit
ILI	Input Leakage Current	$0V \leq V_{IN} \leq V_{CC}$			±1	μΑ
I <sub>LO</sub>	Output Leakage Current	$0V \le V_{OUT} \le V_{CC}$			±1	μΑ
I <sub>CC1</sub>	Supply Current	Switch Freq = 400kHz			400	μΑ
I <sub>CC2</sub>	Supply Current (standby)	$SCL,SDA = V_{CC} - 0.3V$			100	μΑ
V <sub>IL</sub>	Input Low Voltage		-0.3		0.3V <sub>CC</sub>	V
V <sub>IH</sub>	Input High Voltage		0.7V <sub>CC</sub>		V <sub>CC</sub> + 0.3	V
\/-·	Output Low Voltage	I <sub>OL</sub> = 3.0mA			0.4	V
V <sub>OL</sub>	Output Low Voltage (Open Drain) <sup>(5)</sup>	I <sub>OL</sub> = 10mA			0.4	V
	Pull-up Supply Voltage (Open Drain)	ĪRQ/OUT/FT/SQW			5.5	V
V <sub>BAT</sub> <sup>(2)</sup>	Battery Supply Voltage		2.5 <sup>(3)</sup>	3	3.5 <sup>(4)</sup>	V
I <sub>BAT</sub>	Battery Supply Current	$T_A = 25$ °C, $V_{CC} = 0V$ Oscillator ON, $V_{BAT} = 3V$		0.6	1	μΑ

- Note: 1. Valid for Ambient Operating Temperature: T<sub>A</sub> = -40 to 85°C; V<sub>CC</sub> = 2.0 to 5.5V (except where noted).

  2. STMicroelectronics recommends the RAYOVAC BR1225 or BR1632 (or equivalent) as the battery supply.

  3. After switchover (V<sub>SO</sub>), V<sub>BAT</sub> (min) can be 2.0V for crystal with R<sub>S</sub> = 40KΩ.

  4. For rechargeable back-up, V<sub>BAT</sub> (max) may be considered V<sub>CC</sub>.

  5. For IRQ/FT/OUT/SQW pin (Open Drain)

## **Table 10. Crystal Electrical Characteristics**

Sym	Parameter <sup>(1,2,3)</sup>	Min	Тур	Max	Units
f <sub>O</sub>	Resonant Frequency		32.768		kHz
R <sub>S</sub>	Series Resistance			60	kΩ
C <sub>L</sub>	Load Capacitance		12.5		pF

Note: 1. Externally supplied if using the SO8 package. STMicroelectronics recommends the KDS DT-38: 1TA/1TC252E127, Tuning Fork Type (thru-hole) or the DMX-26S: 1TJS125FH2A212, (SMD) quartz crystal for industrial temperature operations. KDS can be contacted at kouhou@kdsj.co.jp or http://www.kdsj.co.jp for further information on this crystal type.

2. Load capacitors are integrated within the M41T81. Circuit board layout considerations for the 32.768kHz crystal of minimum trace lengths and isolation from RF generating signals should be taken into account.

Figure 19. Power Down/Up Mode AC Waveforms

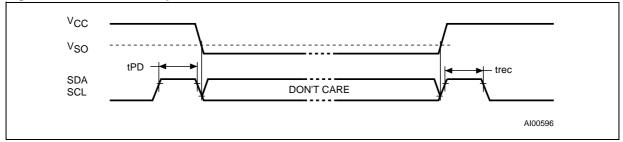


Table 11. Power Down/Up AC Characteristics

Symbol	Parameter <sup>(1,2)</sup>	Min	Тур	Max	Unit
t <sub>PD</sub>	SCL and SDA at V <sub>IH</sub> before Power Down	0			nS
t <sub>rec</sub>	SCL and SDA at V <sub>IH</sub> after Power Up	10			μS

Note: 1.  $V_{CC}$  fall time should not exceed  $5mV/\mu s$ .

Table 12. Power Down/Up Trip Points DC Characteristics

Sym	Parameter <sup>(1,2)</sup>	Min	Тур	Max	Unit
$V_{SO}$	Battery Back-up Switchover Voltage	V <sub>BAT</sub> – 0.80	V <sub>BAT</sub> – 0.50	$V_{BAT} - 0.30$	V

<sup>2.</sup> Valid for Ambient Operating Temperature:  $T_A = -40$  to  $85^{\circ}$ C;  $V_{CC} = 2.0$  to 5.5V (except where noted).

Note: 1. All voltages referenced to V<sub>SS</sub>.

2. Valid for Ambient Operating Temperature: T<sub>A</sub> = -40 to 85°C; V<sub>CC</sub> = 2.0 to 5.5V (except where noted).

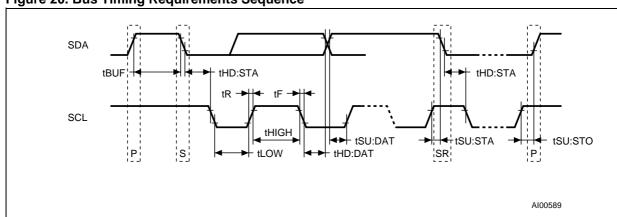


Figure 20. Bus Timing Requirements Sequence

**Table 13. AC Characteristics** 

Sym	Parameter <sup>(1)</sup>	Min	Тур	Max	Units
f <sub>SCL</sub>	SCL Clock Frequency	0		400	kHz
t <sub>LOW</sub>	Clock Low Period	1.3			μs
tHIGH	Clock High Period	600			ns
t <sub>R</sub>	SDA and SCL Rise Time			300	ns
t <sub>F</sub>	SDA and SCL Fall Time	300	ns		
t <sub>HD:STA</sub>	START Condition Hold Time (after this period the first clock pulse is generated)  600				ns
tsu:sta	START Condition Setup Time (only relevant for a repeated start condition)		ns		
t <sub>SU:DAT</sub> (2)	Data Setup Time	100			ns
t <sub>HD:DAT</sub>	Data Hold Time 0				μs
t <sub>SU:STO</sub>	STOP Condition Setup Time	600			ns
t <sub>BUF</sub>	Time the bus must be free before a new transmission can start	1.3			μs

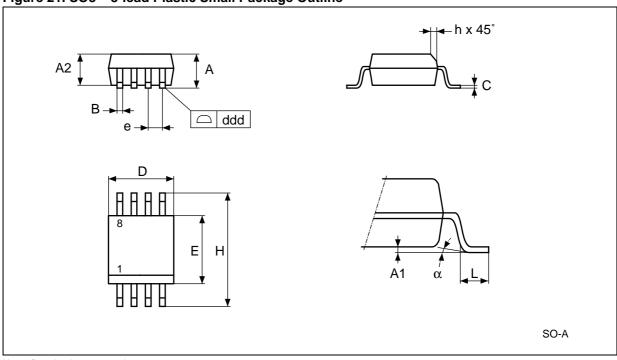
47/ 24/30

Note: 1. Valid for Ambient Operating Temperature: T<sub>A</sub> = -40 to 85°C; V<sub>CC</sub> = 2.0 to 5.5V (except where noted).

2. Transmitter must internally provide a hold time to bridge the undefined region (300ns max) of the falling edge of SCL.

# PACKAGE MECHANICAL INFORMATION

Figure 21. SO8 – 8-lead Plastic Small Package Outline



Note: Drawing is not to scale.

Table 14. SO8 – 8-lead Plastic Small Outline (150 mils body width), Package Mechanical Data

Symb	mm			inches			
Syllib	Тур	Min	Max	Тур	Min	Max	
А		1.35	1.75		0.053	0.069	
A1		0.10	0.25		0.004	0.010	
A2		1.10	1.65		0.043	0.065	
В		0.33	0.51		0.013	0.020	
С		0.19	0.25		0.007	0.010	
D		4.80	5.00		0.189	0.197	
E		3.80	4.00		0.150	0.157	
е	1.27	-	-	0.050	-	-	
Н		5.80	6.20		0.228	0.244	
h		0.25	0.50		0.010	0.020	
L		0.40	0.90		0.016	0.035	
α		0°	8°		0°	8°	
N		8		8			
ddd			0.10			0.004	

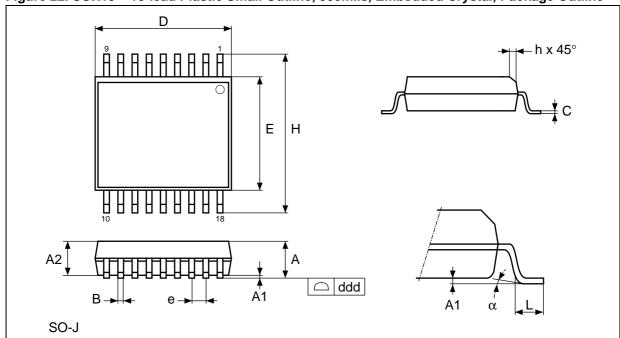


Figure 22. SOX18 – 18-lead Plastic Small Outline, 300mils, Embedded Crystal, Package Outline

Note: Drawing is not to scale.

Table 15. SOX18 – 18-lead Plastic Small Outline, 300mils, Embedded Crystal, Package Mech.

Symbol		millimeters			inches		
	Тур	Min	Max	Тур	Min	Max	
Α		2.44	2.69		0.096	0.106	
A1		0.15	0.31		0.006	0.012	
A2		2.29	2.39		0.090	0.094	
В		0.41	0.51		0.016	0.020	
С		0.20	0.31		0.008	0.012	
D	11.61	11.56	11.66	0.457	0.455	0.459	
ddd			0.10			0.004	
E		7.57	7.67		0.298	0.302	
е	1.27	_	-	0.050	_	-	
Н		10.16	10.52		0.400	0.414	
L		0.51	0.81		0.020	0.032	
α		0°	8°		0°	8°	
N		18	•		18	ı	

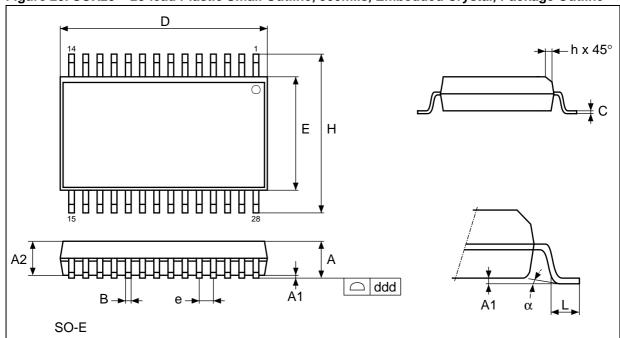


Figure 23. SOX28 – 28-lead Plastic Small Outline, 300mils, Embedded Crystal, Package Outline

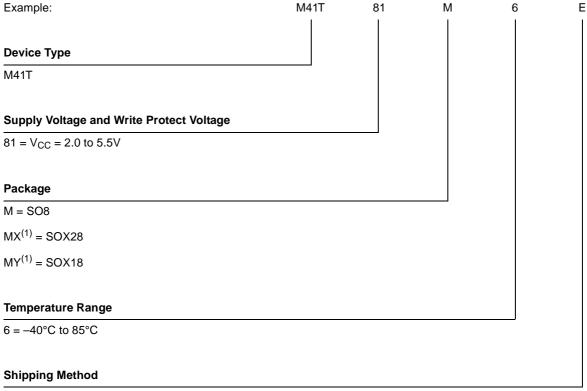
Note: Drawing is not to scale.

Table 16. SOX28 – 28-lead Plastic Small Outline, 300mils, Embedded Crystal, Package Mech.

Symbol		millimeters			inches		
	Тур	Min	Max	Тур	Min	Max	
Α		2.44	2.69		0.096	0.106	
A1		0.15	0.31		0.006	0.012	
A2		2.29	2.39		0.090	0.094	
В		0.41	0.51		0.016	0.020	
С		0.20	0.31		0.008	0.012	
D		17.91	18.01		0.705	0.709	
ddd			0.10			0.004	
Е		7.57	7.67		0.298	0.302	
е	1.27	_	_	0.050	_	_	
Н		10.16	10.52		0.400	0.414	
L		0.51	0.81		0.020	0.032	
α		0°	8°		0°	8°	
N	28				28	1	

# **PART NUMBERING**

## **Table 17. Ordering Information Scheme**



#### For SO8:

blank = Tubes (Not for New Design - Use E)

E = Lead-free Package (ECO PACK®), Tubes

F = Lead-free Package (ECO PACK®), Tape & Reel

TR = Tape & Reel (Not for New Design - Use F)

## For SOX28 and SOX18:

blank = Tubes

TR = Tape & Reel

Note: 1. The SOX28 and SOX18 packages include an embedded 32,768Hz crystal.

For other options, or for more information on any aspect of this device, please contact the ST Sales Office nearest you.

# **REVISION HISTORY**

Table 18. Document Revision History

Date	Version	Revision Details
December 2001	1.0	First Issue
21-Jan-02	1.1	Fix table footnotes (Table 9, 10)
01-May-02	1.2	Modify reflow time and temperature footnote (Table 6)
05-Jun-02	1.3	Modify Data Retention text, Trip Points (Table 12)
10-Jun-02	1.4	Corrected Supply Voltage values (Table 6, 7)
03-Jul-02	1.5	Modify DC Characteristics, Crystal Electrical table footnotes, Preferred Default Values (Table 9, 10, 5)
11-Oct-02	1.6	Add marketing status (Figure 3; Table 17); adjust footnotes (Figure 3; Table 9)
21-Jan-03	1.7	Add embedded crystal package option (Figure 2, 4, 23; Table 16); modified pre- existing mechanical drawing (Figure 21; Table 14).
05-Mar-03	1.8	Correct dimensions (Figure 23; Table 16); remove SNAPHAT® package option
12-Sep-03	2.0	Updated disclaimer, v2.2 template; add SOX18 package (Figure 3, 5, 22; Table 17, 15)
27-Apr-04	3.0	Reformatted; update characteristics (Figure 5, 4, 7, 14, 17, ; Table 1, 6, 9, 12, 17)
17-Jun-04	4.0	Reformatted; add Lead-free information; add dual footprint connections (Figure 6;Table 6, 17)

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